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FIG. 1

(UNIT:mm)

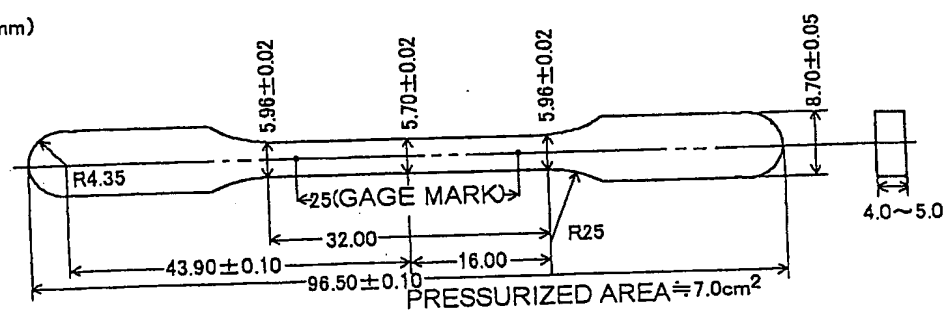


FIG. 2
THE TENSILE STRENGTH OF CuNiSi AND
CuSnNiSi SINTERED MATERIALS (σ_b)

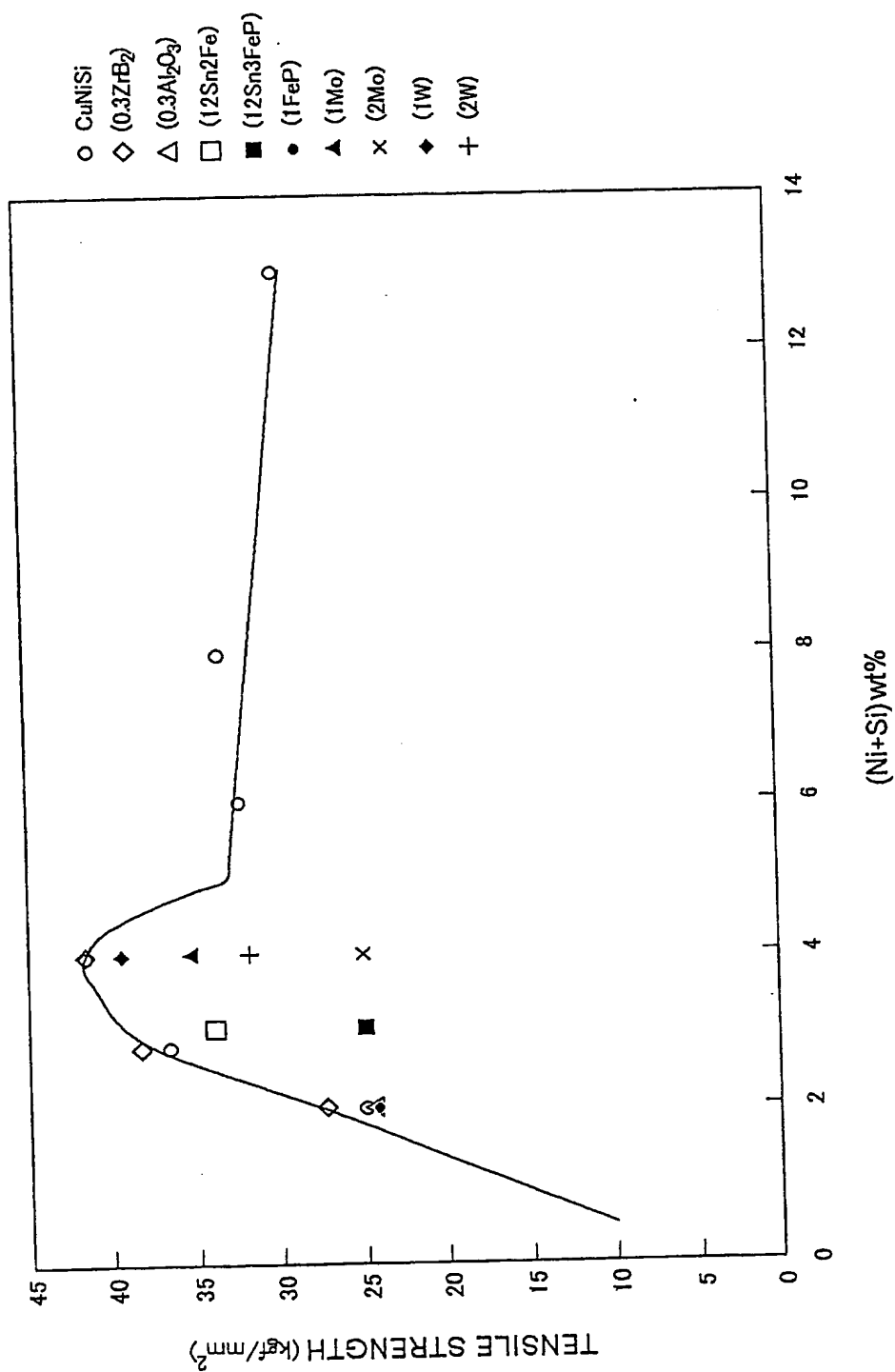
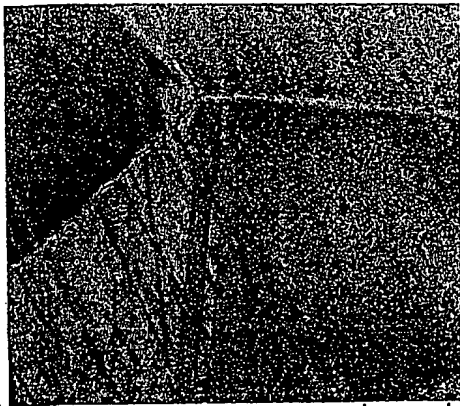


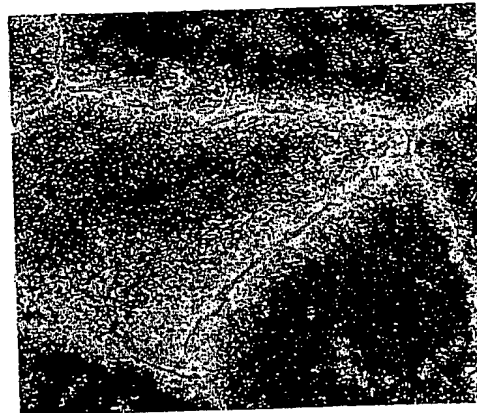
FIG. 3

THE STRUCTURES OF Cu-Ni-Si BASED SINTERED COMPACTS
(A MAGNIFICATION OF $\times 400$)
(SINTERING CONDITION $1100^{\circ}\text{C} \times 1\text{HR}$)

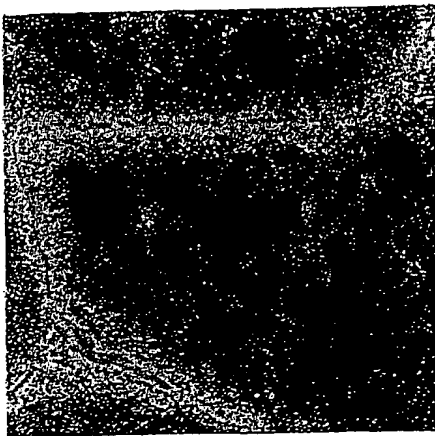


a) Cu-3Ni-1Si

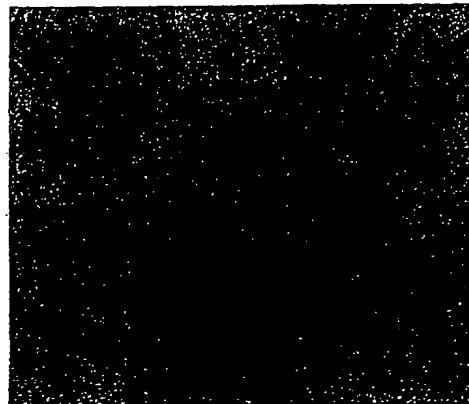
25 μm



b) Cu-4.5Ni-1.5Si



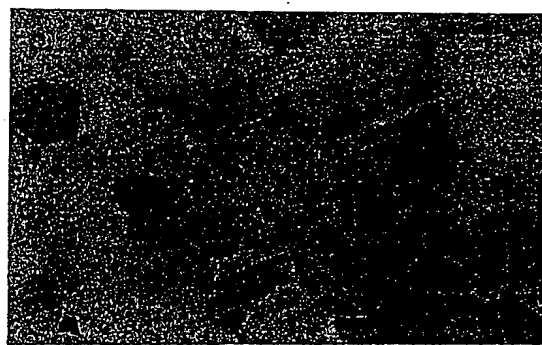
c) Cu-6Ni-2Si



d) Cu-10Ni-3.33Si

FIG. 4

THE STRUCTURE OF A $\text{Cu-3Ni-1Si-0.5SiO}_2$ BASED
SINTERED COMPACT
(A MAGNIFICATION OF $\times 100$)
($1100^\circ\text{C} \times 1\text{HR}$)



0.1mm

FIG. 5

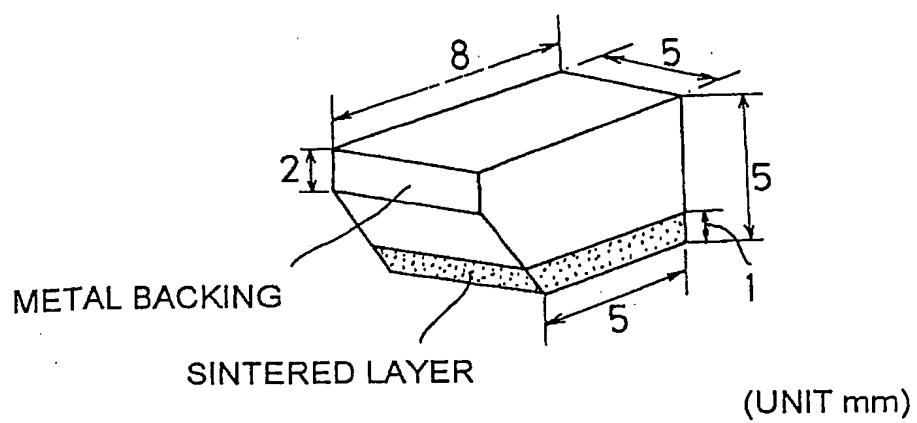
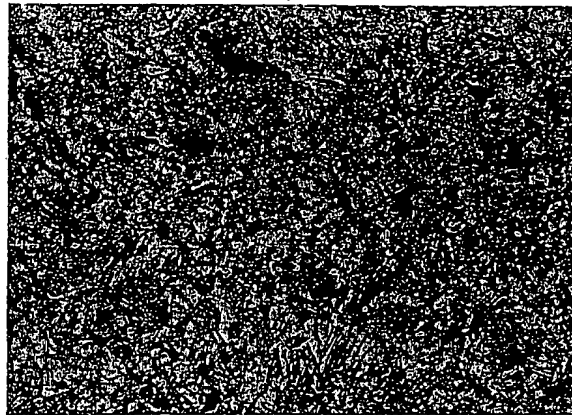


FIG. 6

THE STRUCTURE OF A Cu-10Sn-10Ni-0.55FeP-3Pb (B16)
BASED SINTERED COMPACT
(850°C × 1HR)



25 μ m

FIG. 7

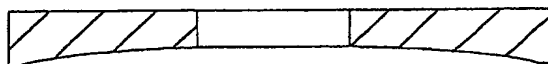


FIG. 8

